Support Home > Product Specifications > Processors

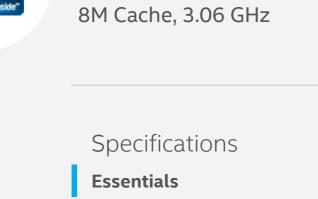
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Intel<sup>®</sup> Core<sup>™</sup> i7-880 Processor

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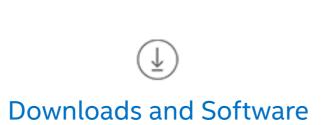
Compatible Products

Downloads and Software

Medicals formerly same field	Essentials	Export spo	حداداله
Decision	Product Collection	Legacy Intel® Core™ Processors	
### ### ### ### ### ### ### ### ### ##	Code Name	Products formerly Lynnfield	
Seaton   Decomposition   De	Vertical Segment	Desktop	
Cause   Description   Cause	Processor Number	i7-880	
### Deformance #### Comes	Status	Discontinued	
Performance	Launch Date ?	Q2'10	
### ### ### ### ### ### ### ### ### ##	Lithography ?	45 nm	
Mol Course	Recommended Customer Price ?	N/A	
M Cores			
### Count   10   10   10   10   10   10   10   1	Performance		
######################################	# of Cores ?	4	
Max Turbu Frequency  Anna Turbu Frequency  Anna Speed	# of Threads ?	8	
Carbo (?) 4 MM SmartLabbe Sus Speed (?) 2 SGT/S DMI Sus Speed (?) 93 W Vib Voltage Range (?) 0.0500/1 a4000V  Supplemental Information  Emcedded Options Available (?) No Debaothers  Ween Memory Specifications  Memory Specifications  Memory Specifications  Mere Memory Specifications  Mere Memory Sure (expendent on memory type) (?) 1a GA Memory Types (?) ODRA 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Mes if of Memory Vibrande (?) 2 COMPAN 1006/1 A82  Memory Specifications  Memory Specifications  Memory Specifications  Memory Specifications  1 Company Types (?) 4 COMPAN 1006/1 A82  Mes if of Memory Types (?) 4 COMPAN 1006/1 A82  Mes if of Memory Types (?) 4 COMPAN 1006/1 A82  Mes if of Memory Types (?) 4 COMPAN 1006/1 A82  Memory Typ	Processor Base Frequency ?	3.06 GHz	
### Support	Max Turbo Frequency ?	3.73 GHz	
### Supports (*) 42.4 GT/y EMM  TIDE (*) 94. W  VID Voltage Range (*) 0.4500V-1.4000V  **Supplemental Information**  **Embadded Opsiens Available (**) No  Datasleet  **Memory Specifications**  **Main Memory Specifications**  **Main of Memory Specifications**  **Main of Memory Specifications**  **Main of Memory Specifications**  **Main of Memory Specifications**  **Physical Address Fatransions (**) 2.0 No  **Expansion Options**  **PCI Express Revisions (**) 2.0  **PCI Express Configurations (**) 1.6 2.0  **Main of PCI Express Lines (**) 1.6 2.0  **Main of PCI Express Lines (**) 1.6 2.0  **Package Specifications**  **Dockets Supported (**) 1.0 LCA1156  **Main of PCI Express Lines (**) 1.6 2.0  **Package Specifications**  **Dockets Supported (**) 1.0 LCA1156  **Main of PCI Express Lines (**) 1.0 No  **Pockage Specifications**  **Dockets Supported (**) 1.0 No  **Memory Specifications**  **Dockets Supported (**) 1.0 No  **Memory Specifications**  **Advanced Technologies**  **Intal** Turbus Docket Technology (**) 1.0 No  **Intal** Poper* Technology (**) 1.0 No  **Intal** Turbus Docket Technology (**) 1.0 No  **Intal** Poper* Technology (**) 1.0 No  **Intal** Turbus Docket		8 MB SmartCache	
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Memory Specifications  Max Memory Size (dependent on memory type) ② 15 GB  Max Memory Size (dependent on memory type) ② 20 GBR 1066/1333  Max for Memory Channels ② 2 GBR 1066/1333  Max for Memory Dandwidth ⑦ 21 GBR 1066/1333  Max for Memory Dandwidth ⑦ 21 GBR 1066/1333  Max for Memory Dandwidth ⑦ 20 GBR 1066/1333  Max for Memory Supported 1 ② No  Expansion Options  PCI Express Revision ② 2.0  PCI Express Revision ② 15 GBR 106		NI a	
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Max # of Memory Size (dependent on memory type) ① DR3 1066/1333  Max # of Memory Channels ① 2  Max Memory Channels ① 2  Max Memory Channels ① 36-bit  ECC Memory Supported ① No  Expansion Options  PCI Express Revision ② 2.0  PCI Express Revision ② 2.0  PCI Express Revision ② 1416, 2x8  Max # of PCI Express Lanes ③ 16  Package Specifications  Sockets Supported ② LGA1156  Max CPU Configuration 1 1  Tools ② 72.7°C  Package Size  a of Processing Die Translators 774 million  Low Holtogen Options Available See MDDS  Advanced Technology ② 1.0  Intel® Virtualization Technology ① 1.0  Intel® Virtualization Technology ② 1.0  Intel® Virtualization Technology ② 1.0  Intel® Virtualization Technology ① 1.0  Intel® Virtualization Technology ② 1.0  Intel® Virtualization Technology ③ 1.0  Intel® Virtualization Technology ③ 1.0  Intel® Virtualization Technology ③ 1.0  Intel® Size 4.2  Intel® Size 4.2  Intel® Size 4.2  Intel® Size 5.2  Intel® Size 4.2  Intel® Demand Based Switching ② 1.0  Intel® Demand Based Switching ③ 1.0  Intel® System Switching 3.0  Intel® System Switching 3.0  Intel® System Switching 3.0  Intel® System Switching 3.0  Intel®	Datasheet	View now	
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Max # of Memory Channels ① 2  Max Memory Bandwidth ② 21 GB/s  Physical Address Extensions ② 36-bit  ECC. Memory Supported ② No  Expansion Options  PCI Express Revelaton ③ 2.0  PCI Express Revelaton ③ 1416, 2x8  Max # of PCI Express Lances ③ 16  Package Specifications  Sockets Supported ② LGA1156  Max CPU Configuration 1 1  TCASC ② 72.7°C  Package Size 37,5mm x 37,5mm  Processing Die Tronslators 72.4 million  Low Halogen Options Available See MDDS  Advanced Technology 1 1.0  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® Yurva Listended Page Tables (EPT) 1 ② Yes  Intel® SEA.2  Idle States ② Yes  Intel® SEA.2  Idle States ② Yes  Intel® Option Sea		40.00	
Max of Memory Channels (?) 21 GB/s  Physical Address Extensions (?) 36-bit  ECC Memory Supported (?) No  Expansion Options  PCI Express Revision (?) 2D  PCI Express Revision (?) 116, 2x8  Max of of PCI Express Lanes (?) 16  Package Specifications  Sockets Supported (?) LGA1156  Max CPU Configuration 1 1  TCASS (?) 72,2°C  Puckage Size 206 mm²  Processing Die Size 206 mm²  If of Processing Die Transistors 774 million  Low Haltogen Options Available See MDDS  Advanced Technologies  Intel® VorTundikazion Technology (?) 10  Intel® SEE 4.2  Idle States (?) 10  Intel® Demand Based Switching (?) 10  Thermal Monitoring Technologies (?) No  Thermal Monitoring Technologies (?) No			
Max Memory Bandwidth ③ 21 G8/s Physical Address Extensions ② 36-bit  ECC Memory Supported ⑥ 20 Expansion Options  PCI Express Revision ④ 2.0 PCI Express Configurations ¹ ① 1x16, 2x8 Max # of PCI Express Lance ⑥ 16 Max # of PCI Express Lance ⑥ 16 Max CPU Configuration  1			
Physical Address Extensions ? 36-bit  ECC Memory Supported ? 9  Expansion Options  PCI Express Revision ? 2.0  PCI Express Revision ? 1416, 2x8  Max # of PCI Express Lanes ? 16  Package Specifications  Sockets Supported ? 16  Max CPU Configuration 1  TCASE ? 2.7°C  Package Size 37.5mm x 37.5mm  Processing Die Transistors 74 million 52  Low Halogen Options Available 52  Advanced Technologies  Intel* Turbo Boost Technology ? 10  Intel* Virtualization Technology (VT-d) ? Yes  Intel* Virtualization Technology for Directed I/O (VT-d) ? Yes  Intel* Virtualization Technology for Directed I/O (VT-d) ? Yes  Instruction Set Extenology ? 10  Instruction Set Extenology ? 10  Instruction Set Extenology ? Yes  Instruction Se			
Expansion Options  PCI Express Revision ① 2.0  PCI Express Revision ① 1x16, 2x8  Max # of PCI Express Lanes ② 16  Package Specifications  Sockets Supported ① 1.0A1156  Max CPU Configuration 1  TCASE ① 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Transistors 296 mm²  Not Place of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technology 1 ② 1.0  Intel® Vervo" Technology 1 ② 1.0  Intel® Vervo" Technology 1 ② 1.0  Intel® Vervo" Technology 1 ① 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0  Intel® Virtualization Technology 1 ① 1.0  Intel® Virtualization Technology 1 ① 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0  Intel® VT-a with Extended Page Tables (EPT) 1 ② 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0  Intel® Virtualization Technology (VT-d) 1 ② 1.0			
Expansion Options  PCI Express Revision ① 2.0  PCI Express Configurations ② 16  Package Specifications  Sockets Supported ② 16  Package Specifications  LGA1156  Max CPU Configuration 1 1  TCASE ① 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 295 mm² 2  # of Processing Die Size 295 mm² 2  # of Processing Die Size 205 mm² 2  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel* Turbo Boost Technology ↑ ② 1.0  Intel* vPro* Technology ↑ ③ 1.0  Intel* SEE A.2  Intel* Demand Based Switching ③ No  Thermal Monitoring Technologies ⑦ No	Physical Address Extensions ?	36-bit	
PCI Express Revision ② 2.0  PCI Express Configurations ¹ ② 1x16, 2x8  Max # of PCI Express Lancs ③ 16  Package Specifications  Sockets Supported ⑥ LGA1156  Max CPU Configuration 1  T_CASE ⑥ 72.7*C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm² 2  ## of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technology 1 ① 1.0  Intel® vPro" Technology ¹ ① 1.0  Intel® vPro" Technology ¹ ① 1.0  Intel® vPro" Technology ¹ ① 1.0  Intel® vPro" Technology ↑ ② 1.0  Intel® vPro" Technolog	ECC Memory Supported ‡ ?	No	
PCI Express Revision ② 2.0  PCI Express Configurations * ② 1x16, 2x8  Max # of PCI Express Lancs ③ 16  Package Specifications  Sockets Supported ② LGA1156  Max CPU Configuration 1 1  T_CASE ② 72.7*C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm² 2  ## of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technology* ① 1.0  Intel® vPro" Technology* ① Yes  Intel® vPro" Technology * ② Yes  Intel® vFro" Technology * ② Yes  Intel® vFro Technology * ② Yes  Intel® * VFro with Extended Page Tables (EPT) * ② Yes  Intel® * VFro with Extended Page Tables (EPT) * ② Yes  Intel® * SE4.2  ## Intel® * SE4.2  ## Intel® * SE4.2  ## Intel® * Sea * Switching ③ No  Thermal Monitoring Technologies ③ No  Thermal Monitoring Technologies ③ No	Evnancian Ontions		
PCI Express Configurations * ? 1x16, 2x8  Max # of PCI Express Lanes ? 16  Package Specifications  Sockets Supported ? LGA1156  Max CPU Configuration 1  T_CASE ? 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel* Turbo Boost Technology * ? 1.0  Intel* VPro" Technology * ? Yes  Intel* VPro" Technology * ? Yes  Intel* Virualization Technology * ? Yes  Intel* VIra with Extended Page Tables (EPT) * ? Yes  Intel* VIra with Extended Page Tables (EPT) * ? Yes  Instruction Set * ? Yes  Instruction Set * Extensions ? Intel* SEE4.2  Idle States ? Yes  Enhanced Intel SpeedStep* Technology ? Yes  Intel* Demand Based Switching ? No  Thermal Monitoring Technologies ? No			
Package Specifications  Sockets Supported ⑦ LGA1156  Max CPU Configuration 1  T_CASE ② 72_7C  Package Size 37.5mm 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDOS  Advanced Technologies  Intel® Turbo Boost Technology ® 1.0  Intel® VPro" Technology ® 1.0  Intel® VPro " Technology P 1.0  Intel® SEE 4.2  Intel® SEE 4.2  Intel® SEE 4.2  Intel® See 4.0  Intel® See 4.0  Intel® See 5.0  Intel® Demand Based Switching ② 1.0  No  Thermal Monitoring Technologies ② 1.0  Intel® Demand Based Switching ② 1.0  Intel® Demand Based Swi		2.0	
Package Specifications  Sockets Supported ② LGA1156  Max CPU Configuration 1  TCASE ③ 72.7°C  Package Size 72.6 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDS  Advanced Technologies  Intel® Turbo Boost Technology ® 1.0  Intel® vPro® Technology ® 2 Yes  Intel® Virtualization Technology ® 2 Yes  Intel® Virtualization Technology Proceed I/O (VT-d) ® 2 Yes  Intel® Virtualization Technology Proceed I/O (VT-d) ® 2 Yes  Intel® Virtualization Technology Proceed I/O (VT-d) ® 2 Yes  Intel® Virtualization Technology Proceed I/O (VT-d) ® 2 Yes  Intel® 44 ® 2 Yes  Intel® 64 ® 2 Yes  Intel® 64 ® 2 Yes  Intel® SSE4.2  Intel® SSE4.2  Intel® Demand Based Switching ® No  Thermal Monitoring Technologies ② No	PCI Express Configurations <sup>‡</sup> ?	1x16, 2x8	
Sockets Supported ① LGA1156  Max CPU Configuration 1  Tease ② 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel® Turbo Boost Technology ® 1.0  Intel® vPro" Technology ® 2 Yes  Intel® VIrtualization Technology (VT-x) ® 2 Yes  Intel® VIrtualization Technology (VT-x) ® 3 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 4 Yes  Intel® SEE4.2  Idle States ② Yes  Enhanced Intel SpeedStep® Technology ② Yes  Enhanced Intel SpeedStep® Technology ② Yes  Enhanced Intel SpeedStep® Technology ② Yes  Intel® Demand Based Switching ② No  Thermal Monitoring Technologies ③ No	Max # of PCI Express Lanes ?	16	
Sockets Supported ① LGA1156  Max CPU Configuration 1  Tease ② 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel® Turbo Boost Technology ® 1.0  Intel® vPro" Technology ® 2 Yes  Intel® VIrtualization Technology (VT-x) ® 2 Yes  Intel® VIrtualization Technology (VT-x) ® 3 Yes  Intel® VT-x with Extended Page Tables (EPT) ® 42  Intel® VT-x with Extended Page Tables (EPT) ® 42  Intel® VT-x with Extended Page Tables (EPT) ® 42  Intel® VT-x with Extended Page Tables (EPT) ® 44  Instruction Set ② 164-bit  Instruction Set ② 164-bit  Instruction Set Extensions ② 164-bit  Intel® SSE4.2  Intel® Demand Based Switching ② No  Thermal Monitoring Technologies ② No	Dackago Specifications		
Max CPU Configuration 1 TCASE ① 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel* Turbo Boost Technology ① 1.0  Intel* Virtualization Technology ① 1.0  Intel* Hyper-Threading Technology ① 1.0  Intel* Virtualization Technology (VT-x) ② 1.0  Intel* Virtualization Technology (VT-x) ③ 1.0  Intel* Open Open Open Open Open Open Open Open			
TCASE ② 72.7°C  Package Size 37.5mm x 37.5mm  Processing Die Size 296 mm²  # of Processing Die Transistors 774 million  Low Halogen Options Available See MDDS  Advanced Technologies  Intel* Turbo Boost Technology ¹ ② 1.0  Intel* Opro* Technology ¹ ② Yes  Intel* Upre-Threading Technology ¹ ② Yes  Intel* Virtualization Technology (VT-x) ² ② Yes  Intel* Virtualization Technology for Directed I/O (VT-d) ² ② Yes  Intel* VT-x with Extended Page Tables (EPT) ¹ ② Yes  Instruction Set ② 64-bit  Instruction Set Extensions ② Intel* SSE4.2  Idle States ② Yes  Enhanced Intel SpeedStep* Technology ② Yes  Intel* Demand Based Switching ③ No  Thermal Monitoring Technologies ③ No	Sockets Supported ?	LGA1156	
Package Size  Processing Die Size  # of Processing Die Transistors  # of Processing Die Transistors  Low Halogen Options Available  # of Processing Die Transistors  Advanced Technologies  Intel® Turbo Boost Technology®	Max CPU Configuration	1	
Processing Die Size # of Processing Die Transistors  Try million  Advanced Technologies  Intel® Turbo Boost Technology® ? 1.0  Intel® VPro® Technology® ? Yes  Intel® Upper-Threading Technology® ? Yes  Intel® Virtualization Technology (VT-x)® ? Yes  Intel® Virtualization Technology (VT-x)® ? Yes  Intel® VIT-x with Extended Page Tables (EPT)® ? Yes  Intel® VIT-x with Extended Page Tables (EPT)® ? Yes  Instruction Set ? Yes  Instruction Set Extensions ? Intel® SSE4.2  Idle States ? Yes  Intel® Demand Based Switching ? No  Thermal Monitoring Technologies ? No	T <sub>CASE</sub> ?	72.7°C	
# of Processing Die Transistors  Town Halogen Options Available  Advanced Technologies  Intel* Turbo Boost Technology † ② 1.0  Intel* VPro" Technology † ② Yes  Intel* Hyper-Threading Technology † ② Yes  Intel* Virtualization Technology (VT-x) † ③ Yes  Intel* Virtualization Technology for Directed I/O (VT-d) † ② Yes  Intel* Options Applied Technology for Directed I/O (VT-d) † ② Yes  Intel* Options Options Applied Technology for Directed I/O (VT-d) † ② Yes  Intel* Options Opt	Package Size	37.5mm x 37.5mm	
Advanced Technologies  Intel* Turbo Boost Technology † ? 1.0  Intel* VPro" Technology † ? Yes  Intel* Virtualization Technology (VT-x) † ? Yes  Intel* Virtualization Technology for Directed I/O (VT-d) † ? Yes  Intel* Of Page Tables (EPT) † Yes	Processing Die Size	296 mm <sup>2</sup>	
Advanced Technologies  Intel* Turbo Boost Technology † ? 1.0  Intel* VPro" Technology † ? Yes  Intel* Myper-Threading Technology † ? Yes  Intel* Virtualization Technology (VT-x) † ? Yes  Intel* Virtualization Technology for Directed I/O (VT-d) † ? Yes  Intel* VT-x with Extended Page Tables (EPT) † ? Yes  Intel* Of 4 ? Yes  Instruction Set ? Intel* SSE4.2  Idle States ? Yes  Enhanced Intel SpeedStep* Technology ? Yes  Intel* Demand Based Switching ? No  Thermal Monitoring Technologies ? No	# of Processing Die Transistors	774 million	
Intel® Turbo Boost Technology † ?  Intel® VPro™ Technology † ?  Yes  Intel® Hyper-Threading Technology † ?  Yes  Intel® Virtualization Technology (VT-x) † ?  Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ?  Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ?  Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ?  Yes  Intel® 64 † ?  Instruction Set ?  Intel® SSE4.2  Idle States ?  Yes  Intel® SSE4.2  Intel® Demand Based Switching ?  No  Thermal Monitoring Technologies ?  No	Low Halogen Options Available	See MDDS	
Intel® Turbo Boost Technology † ? Yes  Intel® VPro™ Technology † ? Yes  Intel® Hyper-Threading Technology † ? Yes  Intel® Virtualization Technology (VT-x) † ? Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ? Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ? Yes  Intel® Virtualization Technology for Directed I/O (VT-d) † ? Yes  Intel® 64 † ? Yes  Instruction Set ? Yes  Instruction Set Extensions ? Intel® SSE4.2  Idle States ? Yes  Intel® Demand Based Switching ? No  Thermal Monitoring Technologies ? No			
Intel® VPro® Technology® ? Yes  Intel® Hyper-Threading Technology (VT-x)® ?  Intel® Virtualization Technology (VT-x)® ?  Intel® Virtualization Technology (VT-x)® ?  Intel® Virtualization Technology for Directed I/O (VT-d)® ?  Intel® VT-x with Extended Page Tables (EPT)® ?  Yes  Intel® VT-x with Extended Page Tables (EPT)® ?  Yes  Instruction Set ②	Advanced Technologies		
Intel® Hyper-Threading Technology ® Yes  Intel® Virtualization Technology (VT-x)® Yes  Intel® Virtualization Technology for Directed I/O (VT-d)® Yes  Intel® VT-x with Extended Page Tables (EPT)® Yes  Intel® 64® ® Yes  Instruction Set ® 64-bit  Instruction Set Extensions ® Intel® SSE4.2  Idle States ® Yes  Enhanced Intel SpeedStep® Technology ® Yes  Intel® Demand Based Switching ® No  Thermal Monitoring Technologies ® No	Intel® Turbo Boost Technology ‡ 🕐	1.0	
Intel® Virtualization Technology (VT-x) ‡ ② Yes  Intel® Virtualization Technology for Directed I/O (VT-d) ‡ ② Yes  Intel® VT-x with Extended Page Tables (EPT) ‡ ③ Yes  Intel® 64 ‡ ② Yes  Instruction Set ③ 64-bit  Instruction Set Extensions ② Intel® SSE4.2  Idle States ② Yes  Enhanced Intel SpeedStep® Technology ② Yes  Intel® Demand Based Switching ② No  Thermal Monitoring Technologies ③ No	Intel® vPro™ Technology ‡ 💽	Yes	
Intel® Virtualization Technology for Directed I/O (VT-d) ‡ ? Yes  Intel® VT-x with Extended Page Tables (EPT) ‡ ? Yes  Intel® 64 ‡ ? Yes  Instruction Set ② 64-bit  Instruction Set Extensions ② Intel® SSE4.2  Idle States ② Yes  Enhanced Intel SpeedStep® Technology ② Yes  Intel® Demand Based Switching ② No  Thermal Monitoring Technologies ③ No	Intel® Hyper-Threading Technology ‡ 🕐	Yes	
Intel® Virtualization Technology for Directed I/O (VT-d) ‡ ? Yes  Intel® VT-x with Extended Page Tables (EPT) ‡ ? Yes  Intel® 64 ‡ ? Yes  Instruction Set ② 64-bit  Instruction Set Extensions ② Intel® SSE4.2  Idle States ? Yes  Enhanced Intel SpeedStep® Technology ② Yes  Intel® Demand Based Switching ② No  Thermal Monitoring Technologies ? No	Intel® Virtualization Technology (VT-x) ‡ 🕐	Yes	
Intel® VT-x with Extended Page Tables (EPT) ‡ ? Yes  Intel® 64 ‡ ? Yes  Instruction Set ? 64-bit  Instruction Set Extensions ? Intel® SSE4.2  Idle States ? Yes  Enhanced Intel SpeedStep® Technology ? Yes  Intel® Demand Based Switching ? No  Thermal Monitoring Technologies ? No	Intel® Virtualization Technology for Directed I/O (VT-d) † ?	Yes	
Instruction Set ② Yes  Instruction Set Extensions ③ Intel® SSE4.2  Idle States ③ Yes  Enhanced Intel SpeedStep® Technology ③ Yes  Intel® Demand Based Switching ④ No  Thermal Monitoring Technologies ④ No		Yes	
Instruction Set ? 64-bit Instruction Set Extensions ? Intel® SSE4.2 Idle States ? Yes Enhanced Intel SpeedStep® Technology ? Yes Intel® Demand Based Switching ? No Thermal Monitoring Technologies ? No			
Instruction Set Extensions ? Intel® SSE4.2  Idle States ? Yes  Enhanced Intel SpeedStep® Technology ? Yes  Intel® Demand Based Switching ? No  Thermal Monitoring Technologies ? No			
Idle States ? Yes Enhanced Intel SpeedStep® Technology ? Yes Intel® Demand Based Switching ? No Thermal Monitoring Technologies ? No			
Enhanced Intel SpeedStep® Technology ? Yes  Intel® Demand Based Switching ? No  Thermal Monitoring Technologies ? No			
Intel® Demand Based Switching ? No Thermal Monitoring Technologies ? No			
Thermal Monitoring Technologies ? No			
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Intel® AES New Instructions   No  Intel® Trusted Execution Technology    Vec		No	

More support options for Intel® Core™ i7-880 Processor (8M Cache, 3.06 GHz)





Intel® Trusted Execution Technology ‡ 🕐

Execute Disable Bit ‡ ?



Yes

Yes





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"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology. Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment. For benchmarking data see http://www.intel.com/performance.

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